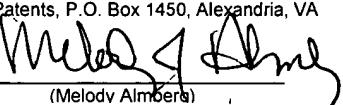
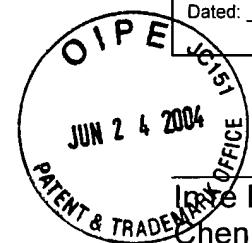


I hereby certify that this correspondence is being deposited with the U.S. Postal Service as Express Mail, Airbill No. EV343595971US, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date shown below.

Dated: 6/29/04 Signature: 
(Melody Almberg)

Docket No.: 291958171US4
Semitool Ref No. P98-0025US8
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Chen et al.

Application No.: 10/695,419

Confirmation No.: 4483

Filed: October 27, 2003

Art Unit: 2818

For: APPARATUS AND METHOD FOR
ELECTROLYTICALLY DEPOSITING
COPPER ON A SEMICONDUCTOR
WORKPIECE

Examiner: P. T. Dang

INFORMATION DISCLOSURE STATEMENT (IDS)

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 CFR 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached PTO/SB/08. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is filed more than three months after the U.S. filing date, OR more than three months after the date of entry of the national stage of a PCT application, AND after the mailing date of the first Office Action on the merits, whichever occurs first, but before the mailing date of a Final Office Action or Notice of Allowance (37 CFR 1.97(c)).

Copies of the references on the PTO/SB/08 are not provided.

The references are not supplied because they were previously cited by or submitted to the Office in a prior application number 10/302,711, filed November 22, 2002, Patent No. 6,638,410 and relied upon in this application for an earlier filing date under 35 U.S.C. 120.

Our check in the amount of \$180.00 covering the fee set forth in 37 CFR 1.17(p) is enclosed. The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 50-0665, under Order No. 291958171US4.

Dated: June 24, 2004

Respectfully submitted,

By Paul Parker

Paul T. Parker
Registration No.: 38,264
PERKINS COIE LLP
P.O. Box 1247
Seattle, Washington 98111-1247
(206) 359-8000
(206) 359-7198 (Fax)
Attorney for Applicant



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Substitute for form 1449A/B/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Sheet	1	of	4	Attorney Docket Number	291958171US4
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Substitute for form 1449A/B/PTO				Complete if Known	
				Application Number	10/695,419-Conf. #4483
				Filing Date	October 27, 2003
				First Named Inventor	LinLin Chen
				Art Unit	2818
				Examiner Name	P. T. Dang
Sheet	2	of	4	Attorney Docket Number	291958171US4

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		Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)			
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Sheet	3	of	4	Filing Date	October 27, 2003
				First Named Inventor	LinLin Chen
				Art Unit	2818
				Examiner Name	P. T. Dang
				Attorney Docket Number	291958171US4

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